

Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
PSA23-11CGKWA	Green (AlGaInP)	White Diffused	14000	39000	Common Anode, Rt. Hand Decimal.
			*5600	*14000	

Notes:

1. Luminous intensity/ luminous Flux: +/-15%.

* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter		Device	Typ.	Max.	Units	Test Conditions
λ peak	Peak Wavelength		Green	574		nm	If=20mA
λ D[1]	Dominant Wavelength		Green	570		nm	If=20mA
$\Delta\lambda$ 1/2	Spectral Line Half-width		Green	20		nm	If=20mA
C	Capacitance		Green	15		pF	VF=0V;f=1MHz
VF[2]	Forward Voltage	A1,A2,D1,D2,P,K	Green	4.2	5.0	V	If=20mA
		B,C,E,F,G,H,J,L,M,N					
		DP		2.1	2.5		
IR	Reverse Current (Per Chip)	A1,A2,D1,D2,P,K	Green		10	uA	VR = 5V
		B,C,E,F,G,H,J,L,M,N			20		
		DP			10		

Notes:

1.Wavelength: +/-1nm.

2.Forward Voltage: +/-0.1V.

3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

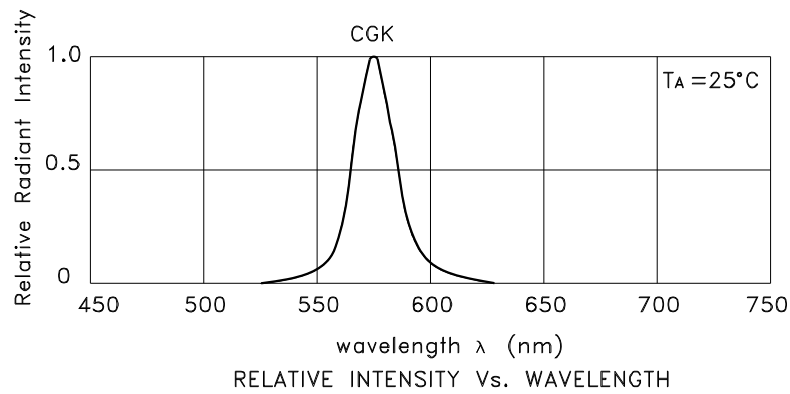
Absolute Maximum Ratings at TA=25°C

Parameter		Green	Units
Power dissipation	A1,A2,D1,D2,P,K	150	mW
	B,C,E,F,G,H,J,L,M,N	300	
	DP	75	
DC Forward Current	A1,A2,D1,D2,P,K	30	mA
	B,C,E,F,G,H,J,L,M,N	60	
	DP	30	
Peak Forward Current [1]	A1,A2,D1,D2,P,K	150	mA
	B,C,E,F,G,H,J,L,M,N	300	
	DP	150	
Reverse Voltage(Per Chip)	A1,A2,D1,D2,P,K	5	V
	B,C,E,F,G,H,J,L,M,N	5	
	DP	5	
Operating / Storage Temperature		-40°C To +85°C	
Lead Solder Temperature [2]		260°C For 3-5 Seconds	

Notes:

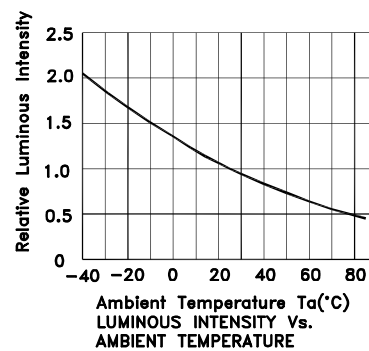
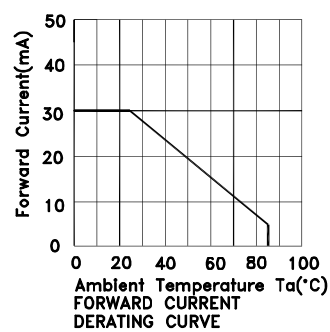
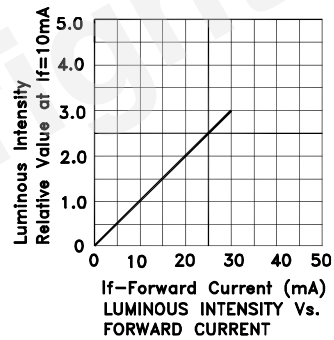
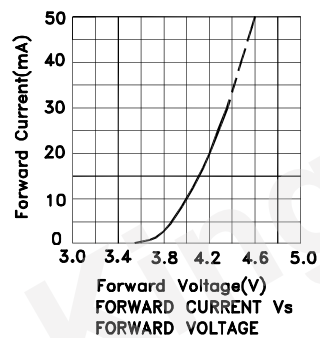
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.



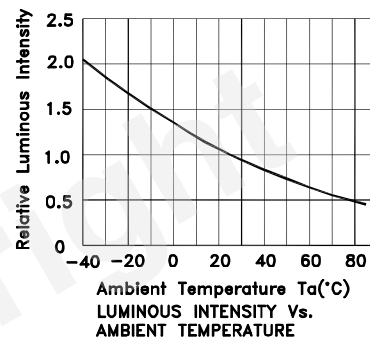
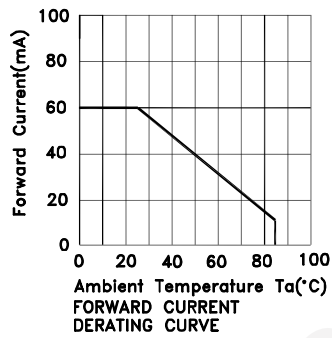
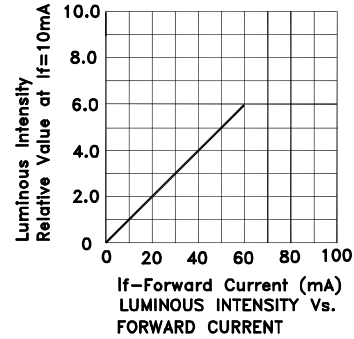
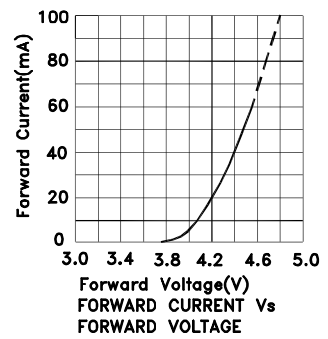
Green

PSA23-11CGKWA



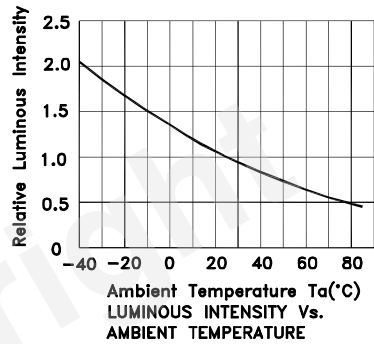
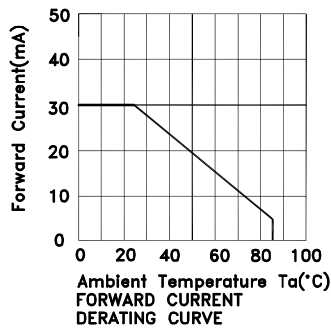
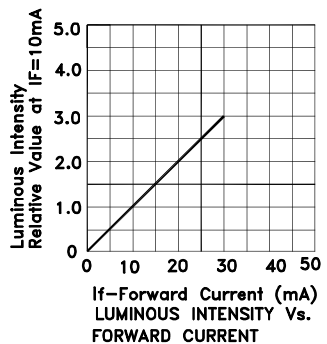
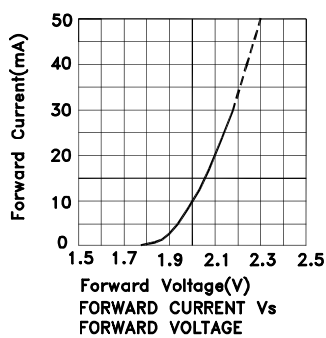
Note:the curves are on the segment a1,a2,d1,d2,p,k.

Green



Note:the curves are on the segment b,c,e,f,g,h,j,i,l,m,n.

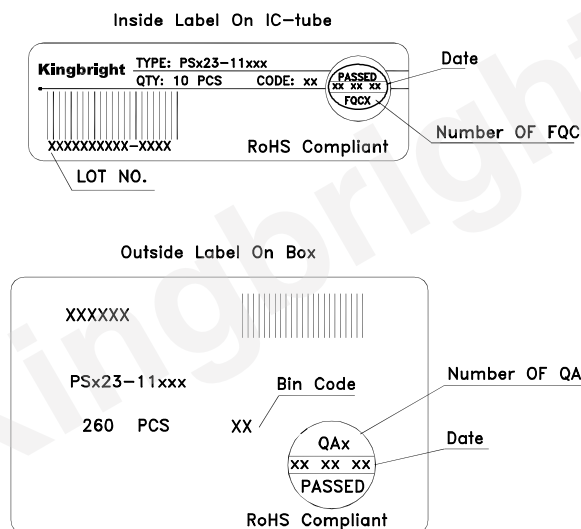
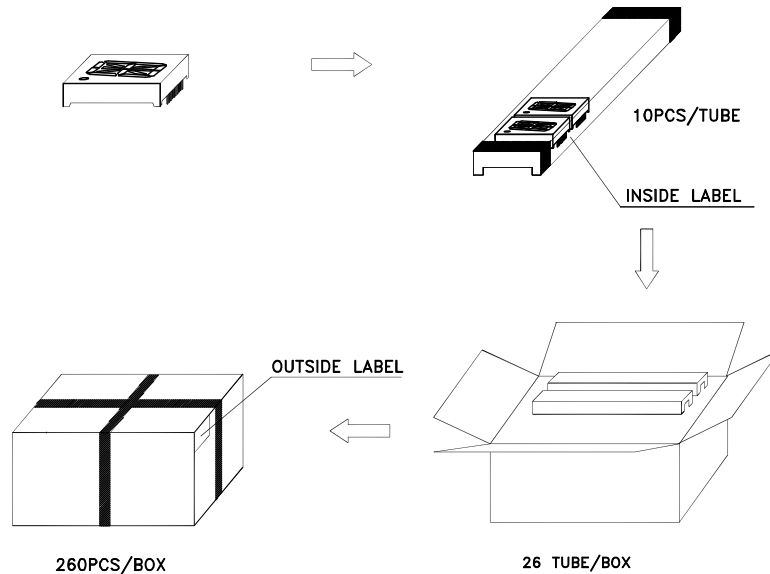
Green



Note: the curves are on the DP.

PACKING & LABEL SPECIFICATIONS

PSA23-11CGKWA



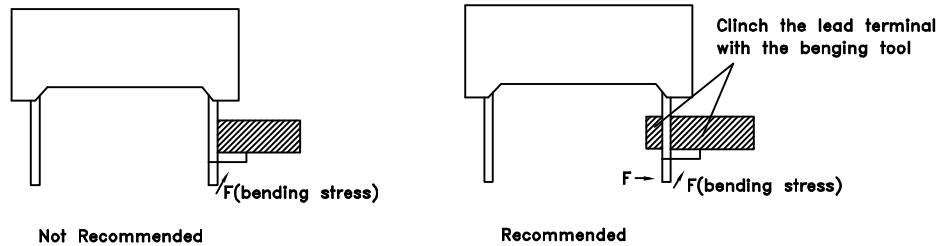
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THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

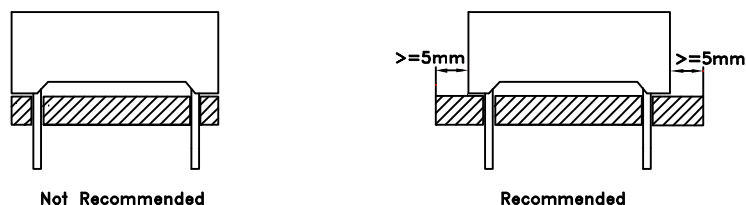


Installation

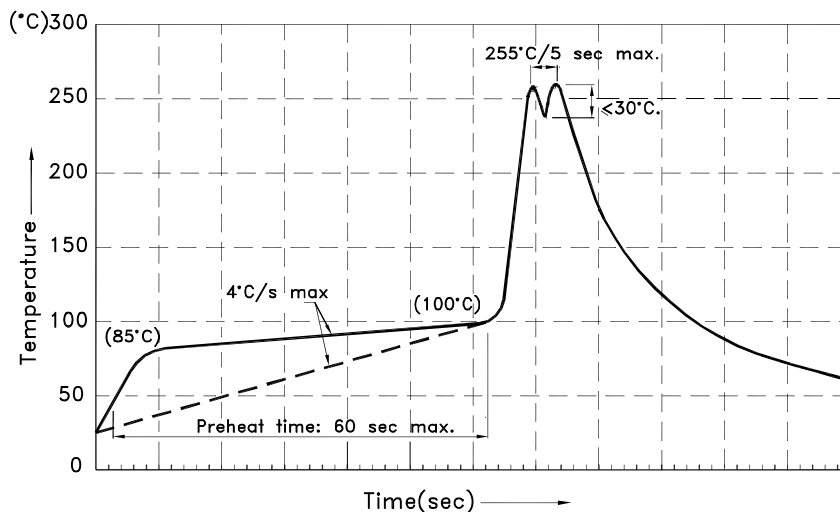
- 1.The installation process should not apply stress to the lead terminals.
- 2.When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



- 3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



Recommended Wave Soldering Profiles:



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.

